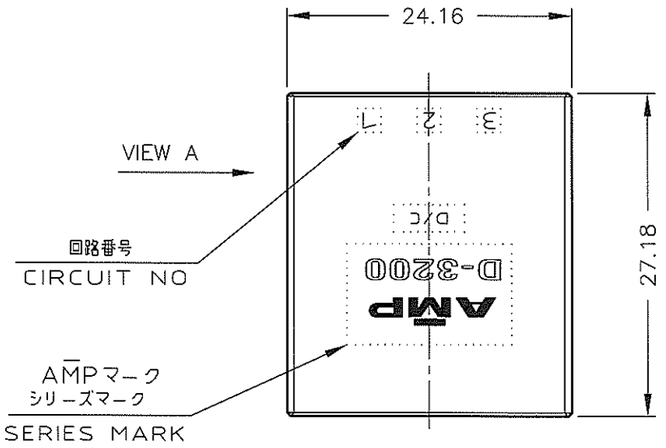
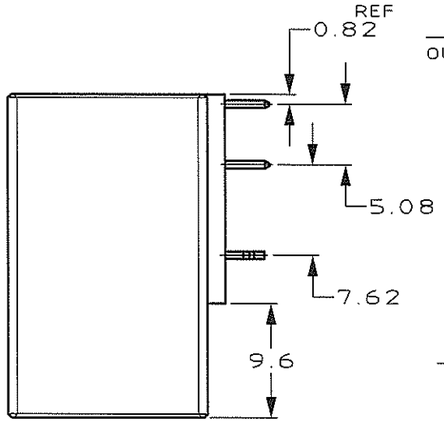
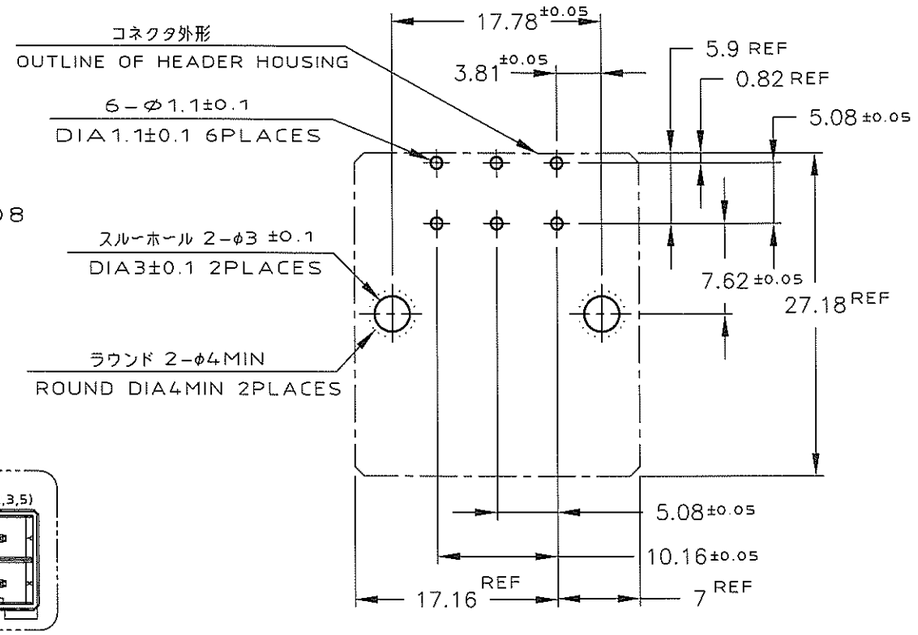
NUMBER 178139

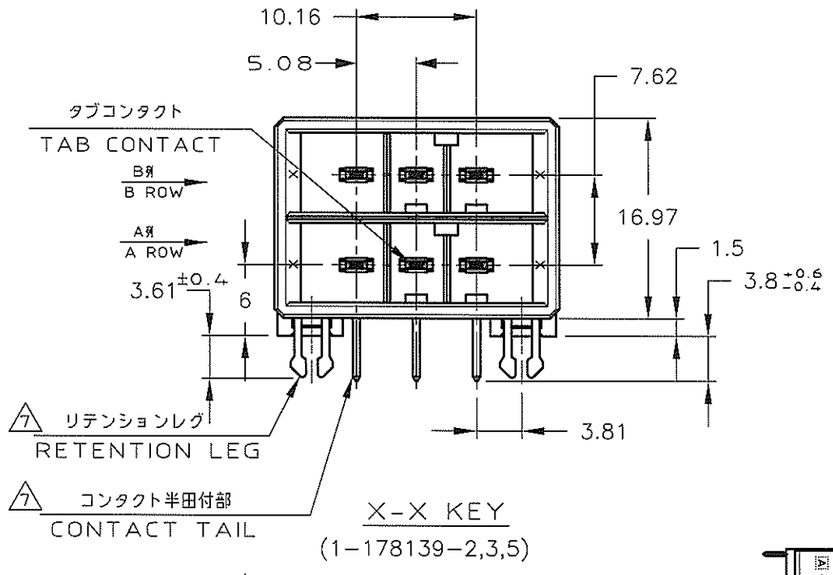
3rd ANGLE PROJECTION

METRIC

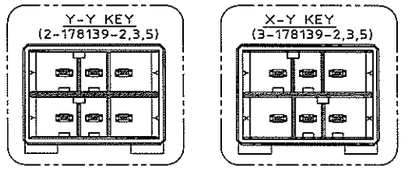


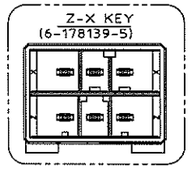


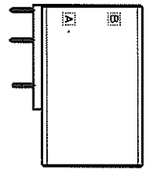




X-X KEY
(1-178139-2,3,5)







VIEW A
(SCALE:1:1)

推奨基板取付け穴寸法
PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

7 4	1,2,3,5,6-178139-5
7 3	1,2,3-178139-3
7 2	1,2,3,4-178139-2
(FINISH)	製品番号 (PART NO.)

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
5. ~~FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~
6. PRODUCT SPEC: 108-5349
7. FINISH(RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地
接触部:0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地
接触部:0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地
接触部:2.0 μm MINスズめっき
5. ~~めっき: リテンションレグとコンタクト半田付部~~
~~: ニッケル下地の上に半田めっき~~
6. 製品規格:108-5349
7. めっき: リテンションレグとコンタクト半田付部
: ニッケル下地の上にスズめっき

LTR	REVISION RECORD	DR	CHK	DATE
E3	REVISED PER ECO-11-005030	RK	HMR	14APR 11

TE Connectivity

WIRE RANGE mm²(AWG -)		INSULATION DIA - mmØ	
MATERIAL	SEE NOTE 注記参照	FINISH	SEE NOTE 注記参照
DR. 20/MAR/'95 K.IKEDA		DE. 20/MAR/'95 K.IKEDA	
CHK. 23/MAR/'95 S.MANABE		APP. 23/MAR/'95 S.MANABE	

NAME
6 POS SINGLE ROW
HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

一般公差 (GENERAL TOLERANCE)
10以下 : ±0.3
10を超え 30以下 : ±0.4
30を超え 100以下 : ±0.45
角度 : ±3°

SIZE	LOC	NUMBER
A3	J	C-178139

SCALE	REV.	SHEET
2-1	E3	1 OF 1

(CUSTOMER DRAWING) 顧客用図面

PRINT DIST

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT